

# Albert M Leung

## List of Publications by Year in descending order

Source: <https://exaly.com/author-pdf/2197854/publications.pdf>

Version: 2024-02-01

12  
papers

109  
citations

1683354

5  
h-index

2053342

5  
g-index

12  
all docs

12  
docs citations

12  
times ranked

105  
citing authors

#	ARTICLE	IF	CITATIONS
1	Intracranial Pressure Telemetry System Using Semicustom Integrated Circuits. IEEE Transactions on Biomedical Engineering, 1986, BME-33, 386-395.	2.5	45
2	A Wideband, Low-Noise Accelerometer for Sonar Wave Detection. IEEE Sensors Journal, 2018, 18, 508-516.	2.4	15
3	Three-axis thermal accelerometer based on buckled cantilever microstructure. , 2008, , .		12
4	MEMS thermal gyroscope with self-compensation of the linear acceleration effect. Sensors and Actuators A: Physical, 2013, 203, 413-420.	2.0	12
5	Monolithically fabricated polymermems 3-axis thermal accelerometers designed for automated wirebinder assembly. Proceedings of the IEEE International Conference on Micro Electro Mechanical Systems (MEMS), 2008, , .	0.0	11
6	The nanogap pirani - a pressure sensor with superior linearity in atmospheric pressure range. Proceedings of the IEEE International Conference on Micro Electro Mechanical Systems (MEMS), 2008, , .	0.0	10
7	Suppression of spurious signals in thermal MEMS gyroscope. , 2012, , .		2
8	Spin-On Glass as a Sacrificial Layer for Patterned Metallization of Compliant SU-8 Microstructures. , 2007, , .		1
9	Undercut Compensation for Xenon Difluoride Etching of Polysilicon Thin-films. , 2007, , .		1
10	Minimize distortion in free-standing sensor plates using electroformed reinforced beam. , 2012, , .		0
11	Correction to "Sensitivity Improvement of Micromachined Convective Accelerometers" [Jun 12 646-655]. Journal of Microelectromechanical Systems, 2018, 27, 374-374.	1.7	0
12	Measurement of In-Package Pressure Using Bondwires. , 2018, , .		0